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Part Number: [0736441016](#)
Status: **Active**
Overview: [hdm](#)
Description: 2.00mm (.079") Pitch HDM® Board-to-Board Backplane Header, Vertical, SMC, Press-Fit, Guide Post Location B, Polarizing Key Position N/A, 144 Circuits

Documents:

3D Model	Test Summary (PDF)
Drawing (PDF)	RoHS Certificate of Compliance (PDF)

Agency Certification

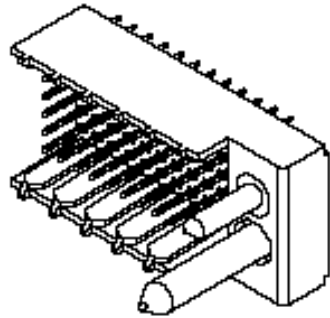
CSA	LR19980
UL	E29179

General

Product Family	Backplane Connectors
Series	73644
Application	Backplane
Comments	Standard Press-Fit
Component Type	PCB Header
Overview	hdm
Product Name	HDM®
Style	N/A

Physical

Circuits (Loaded)	144
Circuits (maximum)	144
Color - Resin	Black, Natural
Durability (mating cycles max)	250
First Mate / Last Break	No
Flammability	94V-0
Guide to Mating Part	Yes
Keying to Mating Part	None
Material - Metal	Phosphor Bronze, Stainless Steel
Material - Plating Mating	Gold
Material - Plating Termination	Gold
Material - Resin	High Temperature Thermoplastic
Number of Columns	24
Number of Pairs	Open Pin Field
Number of Rows	6
Orientation	Vertical
PC Tail Length (in)	0.138 In
PC Tail Length (mm)	3.50 mm
PCB Locator	No
PCB Retention	Yes
PCB Thickness Recommended (in)	0.098 In
PCB Thickness Recommended (mm)	2.50 mm
Packaging Type	Tube
Pitch - Mating Interface (in)	0.079 In
Pitch - Mating Interface (mm)	2.00 mm
Pitch - Term. Interface (in)	0.079 In
Pitch - Term. Interface (mm)	2.00 mm
Plating min: Mating (µin)	30
Plating min: Mating (µm)	0.75
Plating min: Termination (µin)	2
Plating min: Termination (µm)	0.05



Series

image - Reference only

EU RoHS

**ELV and RoHS
Compliant**
REACH SVHC
Contains SVHC: No
Halogen-Free
Status

China RoHS



Not Reviewed

**Need more information on product
environmental compliance?**

Email productcompliance@molex.com
For a multiple part number RoHS Certificate of
Compliance, [click here](#)

Please visit the [Contact Us](#) section for any
non-product compliance questions.

Search Parts in this Series

[73644Series](#)

Mates With

[73632](#) HDM PLUS® Board-to-Board
Daughtercard Receptacle. [73780](#) HDM®
Board-to-Board Daughtercard Receptacle

Application Tooling | FAQ

*Tooling specifications and manuals are
found by selecting the products below.
Crimp Height Specifications are then
contained in the Application Tooling
Specification document.*

Global

Description	Product #
Flat Rock Tooling for	0622013700
Pneumatic Press	
HDM® Backplane	0621001400
Insertion Signal	
Contact Tool	
HDM® Backplane	0622005703
Insertion Head for	
144 Positions	

Polarized to PCB	No	Extraction Tool	0621001000
Stackable	No		
Surface Mount Compatible (SMC)	Yes		
Temperature Range - Operating	-55°C to +105°C		
Termination Interface: Style	Through Hole - Compliant Pin		

Electrical

Current - Maximum per Contact	1A
Data Rate	1.0 Gbps
Real Signals (per 25mm)	75
Shielded	No
Voltage - Maximum	250V AC

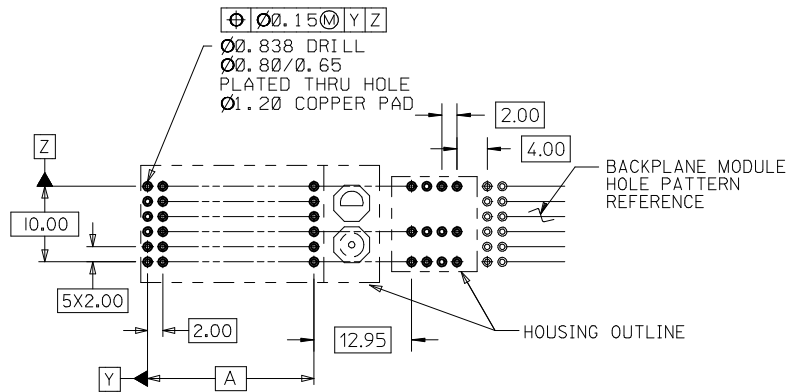
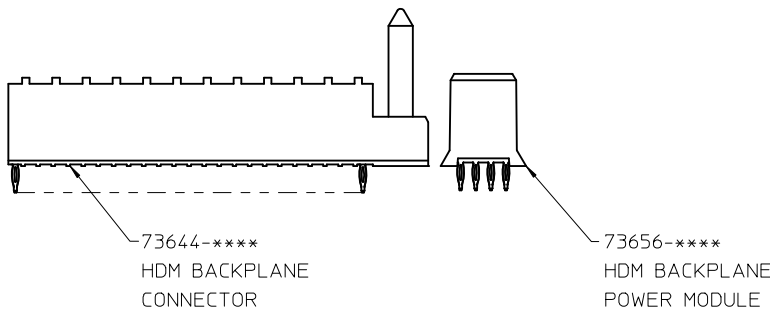
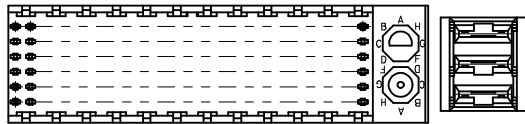
Material Info

Reference - Drawing Numbers

Packaging Specification	PK-70873-0818
Sales Drawing	SD-73644-004, SDA-73644-****

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This document was generated on 05/14/2010
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PCB LAYOUT: COMPONENT SIDE
RECOMMENDED PCB THICKNESS: 2.50 MIN

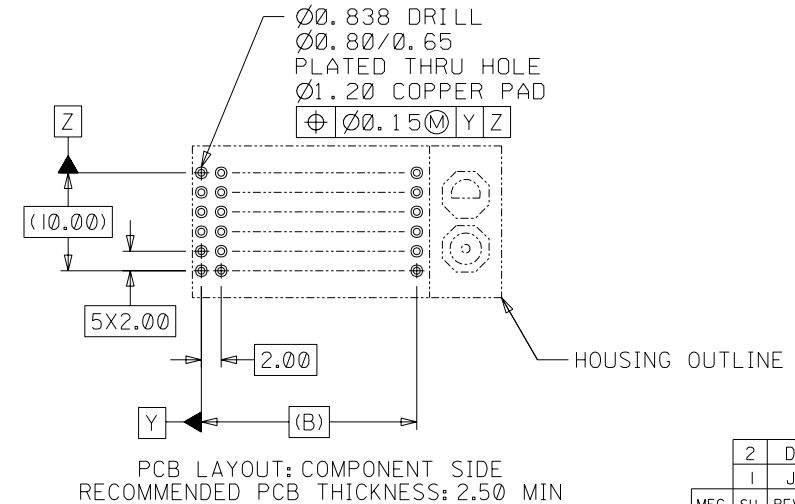
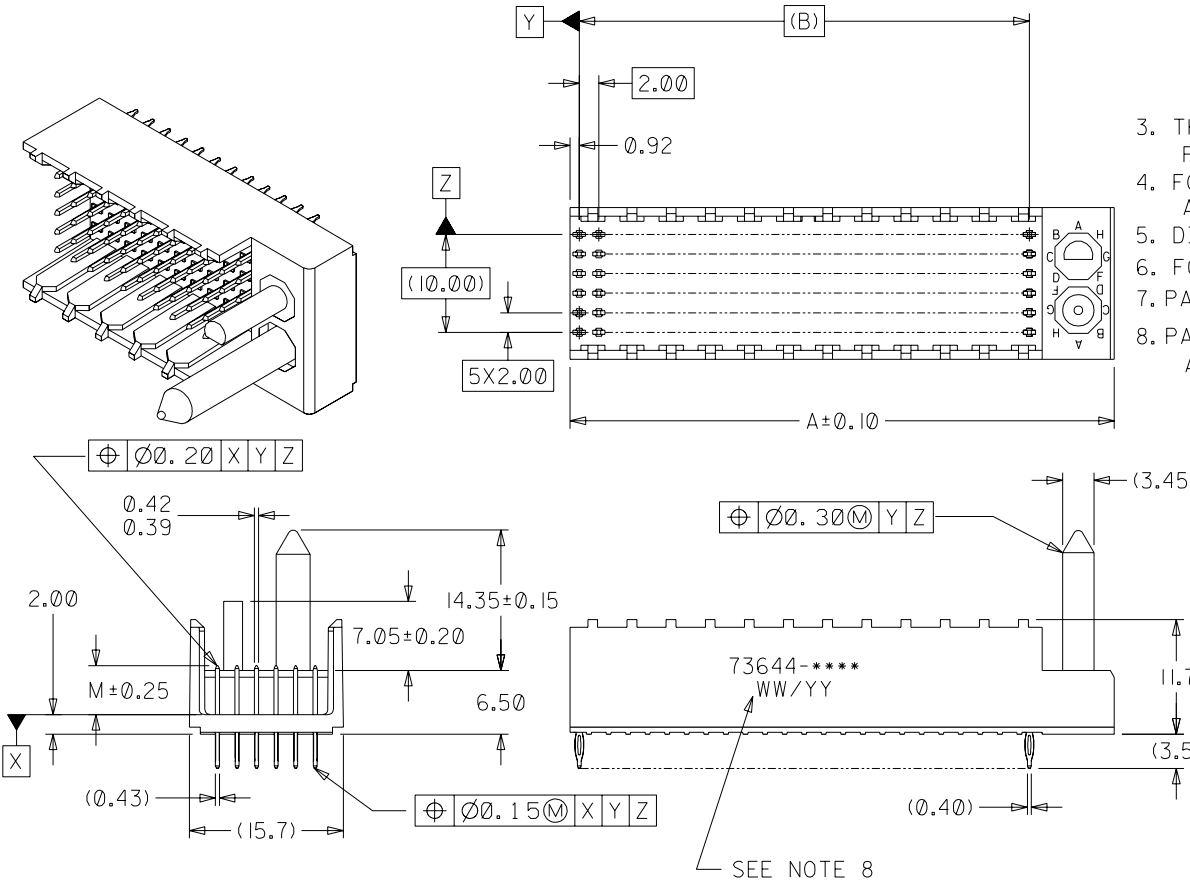
- NOTES:
1. SEE SD-73644-**** FOR ADDITIONAL INFORMATION FOR THE 73644 BACKPLANE MODULE.
 2. SEE SD-73656-*00* FOR ADDITIONAL INFORMATION FOR THE 73656 MODULE.

MATERIAL NUMBER	NUMBER OF SIGNAL CONTACTS	DIM "A"
73644-00**	72	22.00
73644-01**	72	22.00
73644-02**	72	22.00
73644-10**	144	46.00
73644-11**	144	46.00
73644-12**	144	46.00
73644-20**	72	22.00
73644-21**	72	22.00
73644-22**	72	22.00
73644-30**	144	46.00
73644-31**	144	46.00
73644-32**	144	46.00

INITIAL RELEASE EC NO: UCP2009-3131 DRWN:SDANNELLEY 2009/08/05 CHKD:BSMART 2009/08/06 APPR:SMILLER 2009/08/07	REV A	DESCRIPTION QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE MM ONLY		SCALE 2:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION			
				mm	INCH	DRAWN BY SDANNELLEY	DATE 2009/06/26	TITLE PCB LAYOUT FOR 73644 AND 73659 CONNECTORS USED IN CONJUNCTION					
			4 PLACES	± ---	± ---	CHECKED BY BSMART	DATE 2009/06/26						
			3 PLACES	± ---	± .005	APPROVED BY SMILLER	DATE 2009/06/26						
			2 PLACES	± 0.13	± .010	ANGULAR ±1/2°			molex MOLEX INCORPORATED				
			1 PLACE	± 0.25	± ---								
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			MATERIAL NO. N/A		DOCUMENT NO. SD-73644-004		SHEET NO. 1 OF 1			
						SIZE C		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

NOTES:

1. MATERIALS: HOUSING - LIQUID CRYSTAL POLYMER (LCP), GLASS-FILLED, UL94V-0, COLOR: BLACK, TERMINAL - PHOSPHOR BRONZE.
2. FINISHES: SELECTIVE GOLD (Au) IN CONTACT AREA, 0.00076mm MINIMUM THICKNESS; NICKEL (Ni) AND GOLD FLASH OVERALL SELECTIVE GOLD (Au) IN CONTACT AREA, 0.00076mm MIN. THICKNESS; SELECTIVE TIN/LEAD (Sb/Pb) IN TAIL AREA; NICKEL (Ni) OVERALL.
3. THIS PART CONFORMS TO MOLEX PRODUCT SPECIFICATION PS-73670-9999.
4. FOR MIXED CONTACT MATING LENGTHS, CONSULT FACTORY FOR AVAILABILITY.
5. DIMENSIONS ARE IN MILLIMETERS.
6. FOR SPECIFIC MATERIAL NUMBERS, REFER TO SHEET 2.
7. PACKAGE PER PK-70873-0818.
8. PARTS MARKED WITH PART NUMBER AND DATE CODE, ON EITHER SIDE, APPROXIMATELY WHERE SHOWN.



2	D
1	J
MFG.	SH.
REV.	

PCB LAYOUT: COMPONENT SIDE
RECOMMENDED PCB THICKNESS: 2.50 MIN

SEE NOTE 8

		I	REVISED ECR UDT2000-0348 BINGHAM 99/10/12
		H	REVISED ECR UDT1999-0662 BINGHAM 99/05/18
J	REVISED ECR UCP2003-2260 THOMAS 03/04/25	G	REVISED ECR UDT1999-0476 BINGHAM 98/12/21
LTR.	REVISIONS	LTR.	REVISIONS

DIMENSIONS SHOWN (METRIC) INCH	
UNLESS OTHERWISE SPECIFIED TOLERANCES: ANGULAR ± 1/2°	
3 PLACE	± N/A ---
2 PLACE	± N/A ± 0.05
1 PLACE	--- ± 0.10
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	
DRWG. BY	JRR
CHK'D. BY	SMR
APP'D. BY	CAB
SCALE	2 : 1

▽ = 0		▼ = 0		REVISE ONLY ON CAD SYSTEM	
TITLE					
SALES ASSY, HDM BACKPLANE MODULE, POLAR/GUIDE OPTION					
moLEX MOLEX INCORPORATED LISLE, ILL. 60532		SHEET NO. 1 OF 2		DATE 96/12/18	
PART NO.		DRWG. NO.			
SEE CHART		SDA-73644-****			
FILE NAME S73644X1		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INC. AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.			DIV. DA
SIZE B					



Компания «ЭлектроПласт» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

Наши преимущества:

- Оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов;
- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

Помимо этого, одним из направлений компании «ЭлектроПласт» является направление «Источники питания». Мы предлагаем Вам помощь Конструкторского отдела:

- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



Как с нами связаться

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